



HTIP50

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HTIP50 is designed for line operated audio output amplifier switch-mode power supply drivers and other switching applications.

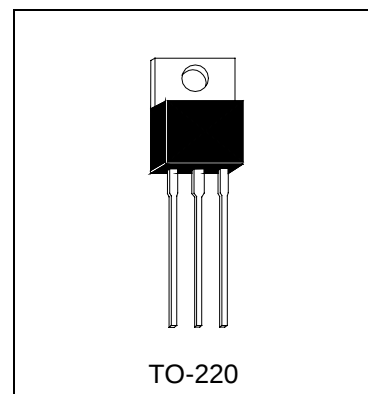
Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -50 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 40 W
Total Power Dissipation (Ta=25°C) 2 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 500 V
BVCEO Collector to Emitter Voltage 400 V
BVEBO Emitter to Base Voltage 5 V
IC Collector Current 1 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	500	-	-	V	IC=1mA, IE=0
BVCEO	400	-	-	V	IC=30mA, IB=0
BVEBO	5	-	-	V	IE=0.1mA, IC=0
IEBO	-	-	1	mA	VEB=5V, IC=0
ICEO	-	-	1	mA	VCE=300V, IB=0
ICES	-	-	1	mA	VCE=500V, VEB=0
*VCE(sat)	-	-	1	V	IC=1A, IB=0.2A
VBE(on)	-	-	1.5	V	IC=1A, VCE=10V
*hFE1	30	-	150		IC=0.3A, VCE=10V
*hFE2	10	-	-		IC=1A, VCE=10V
fT	10	-	-	MHz	IC=0.2A, VCB=10V, f=2MHz

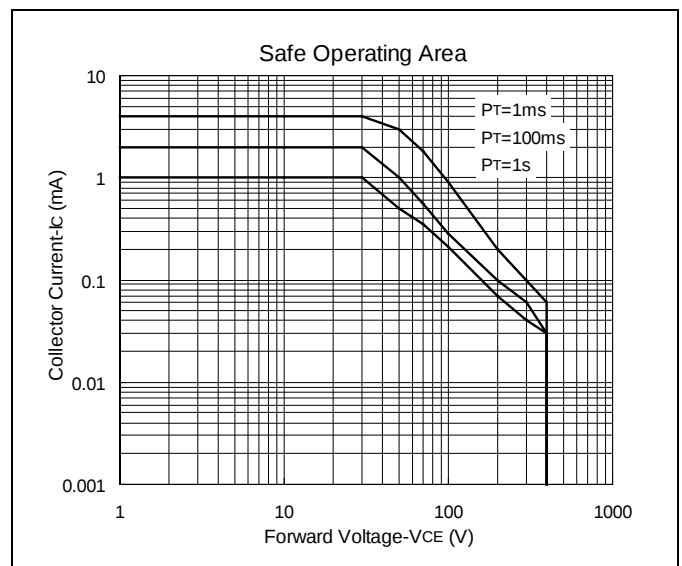
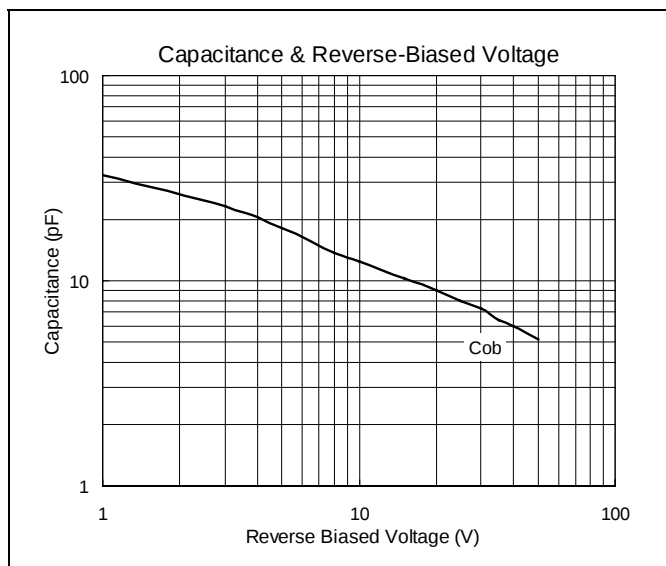
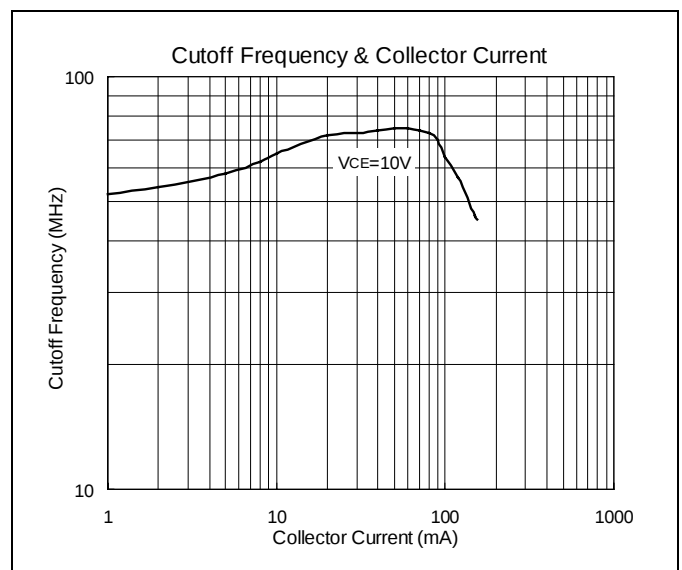
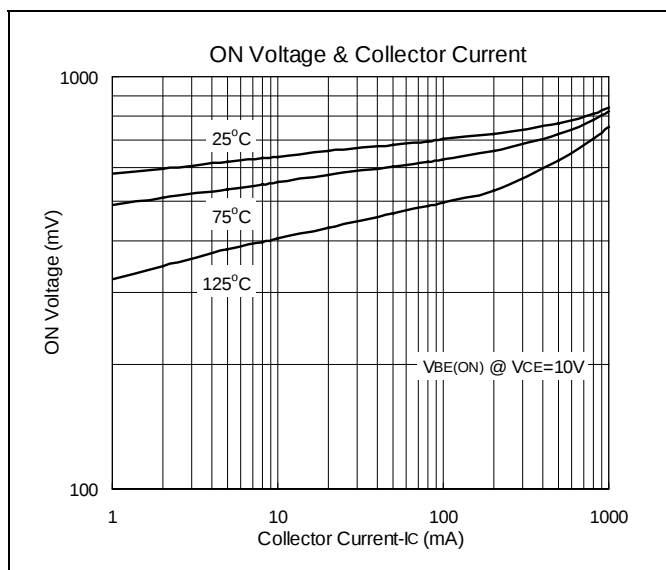
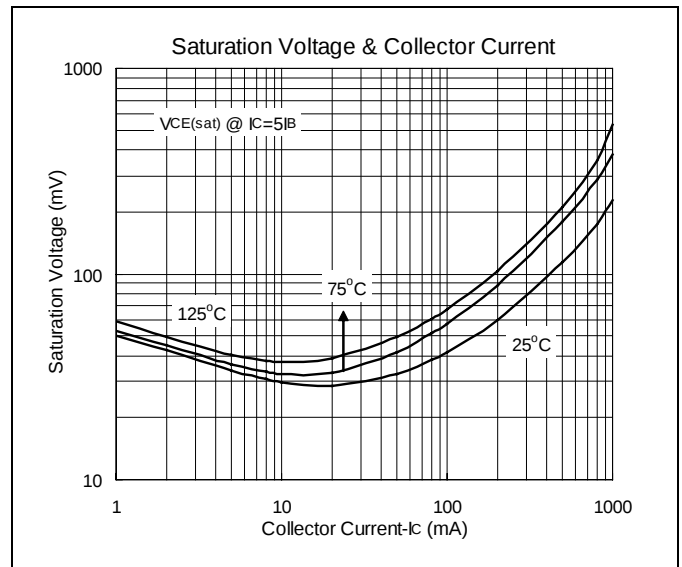
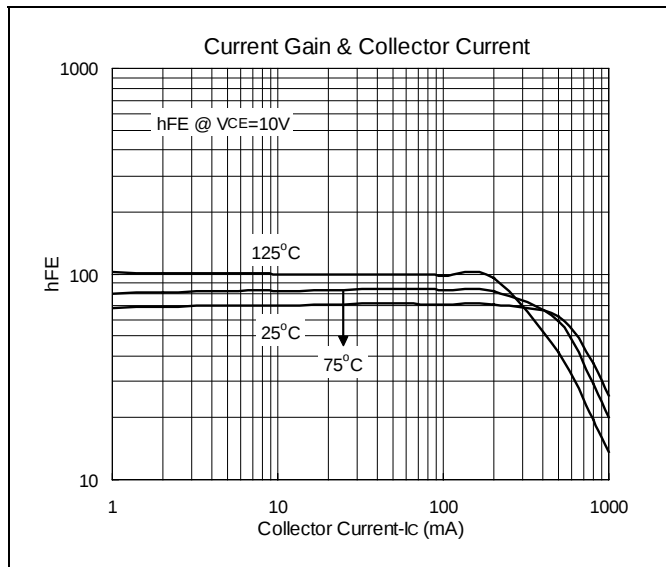
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



TO-220

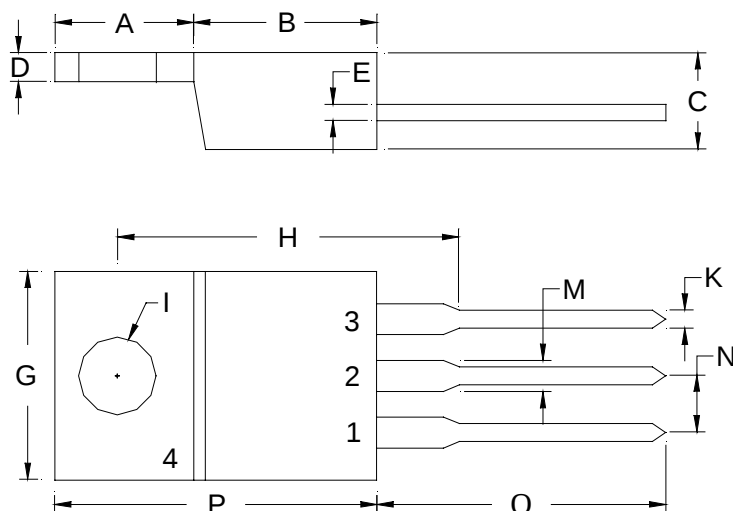


Characteristics Curve



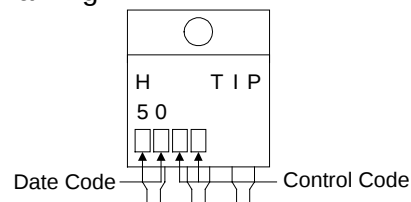


TO-220AB Dimension



3-Lead TO-220AB Plastic Package
HSMC Package Code: E

Marking:



Style: Pin 1.Base 2.Collector 3.Emitter

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

Notes: 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension: millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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